## **AMENDMENTS TO THE SPECIFICATION**

Please amend the paragraph beginning on page 18, line 25 as follows:

The electrode arm portion 30 is vertically movable by a vertical movement motor 132, which is a servomotor, and a ball screw 134, and swingable between the electrolytic solution tray 22 and the substrate processing section 20 by a swing motor, in this embodiment, as described bellow below. A compressed actuator may be used.

Please amend the paragraph beginning on page 19, line 20 as follows:

As shown in FIGS. 5 through 7, the substrate holder 36 has a disk-shaped substrate stage 68 and six vertical support arms 70 disposed at spaced intervals on the circumferential edge of the substrate stage 68 for holding a substrate W in a horizontal plane on respective upper surfaces of the support arms 70. A positioning plate 72 is mounted on an upper end of one of the support arms 70 for positioning the substrate by contacting the end face of the substrate. A pressing finger 74 is rotatably mounted on an upper end of the support arm 70, which is positioned opposite to the support arm 70 having the positioning plate 72, for abutting against an end face of the substrate W and pressing the substrate W to the positioning plate 72 when rotated. Chucking fingers 76 are rotatably mounted on upper ends of the remaining four support arms 70 for pressing the substrate W downwardly and gripping the circumferential edge of the substrate W.

Please amend the paragraph beginning on page 20, line 27 as follows:

As shown in FIGS. 8 and 9, the electrode portion 38 comprises an annular frame 86 fixed to upper ends of vertical support columns 84 mounted on the peripheral edge of the support plate 82 (see FIG. 7), a plurality of, six in this embodiment, first electrodes 88 attached to a lower surface of the annular frame 86 and projecting inwardly, and an annular sealing member 90 mounted on an upper surface of the annular frame 86 in covering relation to upper surfaces of the first electrodes 88. The first electrodes 88 become an anode a cathode during electroplating, and become a cathode an anode during electrolytic etching. The sealing member 90 is adapted to have an inner peripheral edge portion inclined inwardly downwardly and progressively thin-walled, and to have an inner peripheral end suspending downwardly.

Please amend the paragraph beginning on page 26, line 12 as follows:

When the polishing surface 120a of the polishing pad 120 is not in contact with the surface of the substrate W, the electrode head 28 moves up and down (or pivot pivots), together with the pivot arm 26 via the elastic force of the helical compression spring 128. When the pivot arm 26 is lowered, the polishing surface 120a of the polishing pad 120 comes into contact with the surface of the substrate W. When the pivot arm 26 is further lowered, the helical compression spring 128 shrinks. The elastic force of the helical compression spring 128 acts on the polishing pad 120, pressing the polishing surface 120a against the surface of the substrate. The pressing force can be adjusted by adjusting the shrinkage (degree of displacement) of the helical compression spring 128. The pressing force is preferably not higher than 200 g/cm2, with about 70 g/cm2 being particularly preferred. The displacement and the elastic force of the spring may also be obtained by vertical movement of the pivot arm 26 by a compressed air actuator. Though in this embodiment the polishing pad 120 is moved vertically, it is possible to move the substrate holder 36 instead, or move both of them.